

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ALEXANDER PHILIP HARING	02/07/2022
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	18060249
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NAME OF SUBMITTER:	HAROLD H. FOX
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DATE SIGNED:	11/30/2022
Total Attachments: 1	
source=Assignment - Inventor to Formlabs#page1.tif	

ASSIGNMENT

For value received, I the undersigned hereby assign to Formlabs, Inc., having a place of business at 35 Medford Street #1, Somerville, Massachusetts, 02143, and its successors and assigns, the entire right, title and interest, including the right of priority, in, to and under an application for Letters Patent of the United States entitled:

THIOL-ENE SILICONE ADDITIVE FABRICATION

Filing date: February 7, 2022

Application Number: 63/267,645

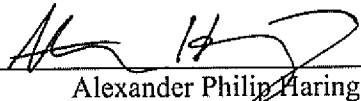
the invention(s) and improvement(s) set forth therein, and any and all continuations, continuations-in-part (CIPs), divisionals, and renewals of and substitutes for said application for said Letters Patent, and any and all Letters Patent of the United States and of countries foreign thereto including the right of priority under the International Convention which may be granted thereon or therefore; and any reissues, or reexaminations, or extensions of said Letters Patent.

I additionally authorize Formlabs, Inc. to file applications in my name for Letters Patent in any country, to be held and enjoyed by Formlabs, Inc., its successors, assigns, nominees or legal representatives, to the full end of the term or terms for which said Letters Patent respectively may be granted, reissued or extended, as fully and entirely as the same would have been held and enjoyed by me had this assignment, and transfer not been made;

And I hereby covenant that I have a full right to convey the entire interest herein assigned, and that I have not executed and will not execute any agreement in conflict herewith, and I further covenant and agree that I will, each time a request is made, and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title to said invention(s) or improvement(s), said application and said Letters Patent to Formlabs, Inc., its successors, assigns, nominees or legal representatives, and I agree to communicate to Formlabs, Inc., or to its nominee, all known facts respecting said invention(s) or improvement(s) said application and said Letters Patent, to testify in any legal proceedings, to sign all lawful papers, to execute all disclaimers and divisionals, continuations, CIPs, reissue and foreign applications, to make all rightful oaths and declarations, and generally to do everything possible to aid Formlabs, Inc., its successors, assigns, nominees and legal representatives to obtain and enforce, for its or their own benefit, proper patent protection for said invention(s) or improvements(s) in any and all countries;

And I hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any country or countries foreign to the United States whose duty it is to issue patents on applications as aforesaid, to issue to Formlabs, Inc., as assignee of the entire right, title and interest, any and all Letters Patent for said invention(s) or improvement(s), including any and all Letters Patent of the United States which may be issued and granted on or as a result of the application aforesaid, in accordance with the terms of this Assignment.

Date Assignment Signed: 2/7/22


Alexander Philip Haring